

LM6142/LM6144 17 MHz Rail-to-Rail Input-Output Operational Amplifiers

Check for Samples: LM6142, LM6144

FEATURES

At $V_S = 5V$. Typ Unless Noted.

- Rail-to-rail Input CMVR -0.25V to 5.25V
- Rail-to-Rail Output Swing 0.005V to 4.995V
- Wide Gain-Bandwidth: 17MHz at 50kHz (typ)
- Slew Rate:
 - Small Signal, 5V/μs
 - Large Signal, 30V/μs
- Low Supply Current 650µA/Amplifier
- Wide Supply Range 1.8V to 24V
- CMRR 107dB
- Gain 108dB with R₁ = 10k
- PSRR 87dB

APPLICATIONS

- Battery Operated Instrumentation
- · Depth Sounders/Fish Finders
- Barcode Scanners
- Wireless Communications
- Rail-to-Rail in-out Instrumentation Amps

Connection Diagrams

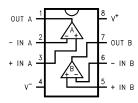


Figure 1. 8-Pin CDIP Top View

DESCRIPTION

Using patent pending new circuit topologies, the LM6142/LM6144 provides new levels of performance in applications where low voltage supplies or power limitations previously made compromise necessary. Operating on supplies of 1.8V to over 24V, the LM6142/LM6144 is an excellent choice for battery operated systems, portable instrumentation and others.

The greater than rail-to-rail input voltage range eliminates concern over exceeding the common-mode voltage range. The rail-to-rail output swing provides the maximum possible dynamic range at the output. This is particularly important when operating on low supply voltages.

High gain-bandwidth with 650µA/Amplifier supply current opens new battery powered applications where previous higher power consumption reduced battery life to unacceptable levels. The ability to drive large capacitive loads without oscillating functionally removes this common problem.

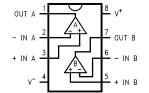


Figure 2. 8-Pin PDIP/SOIC Top View

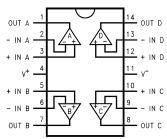


Figure 3. 14-Pin PDIP/SOIC Top View

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These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings (1)(2)

- 10 - 0 - 10 - 10 - 10 - 10 - 10 - 10	
ESD Tolerance (3)	2500V
Differential Input Voltage	15V
Voltage at Input/Output Pin	$(V^{+}) + 0.3V, (V^{-}) - 0.3V$
Supply Voltage (V ⁺ - V ⁻)	35V
Current at Input Pin	±10mA
Current at Output Pin ⁽⁴⁾	±25mA
Current at Power Supply Pin	50mA
Lead Temperature (soldering, 10 sec)	260°C
Storage Temp. Range	−65°C to +150°C
Junction Temperature ⁽⁵⁾	150°C

- (1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.
- (2) If Military/Aerospace specified devices are required, please contact the Texas Instruments Sales Office/ Distributors for availability and specifications.
- (3) Human body model, 1.5kΩ in series with 100pF.
- (4) Applies to both single-supply and split-supply operation. Continuous short circuit operation at elevated ambient temperature can result in exceeding the maximum allowed junction temperature of 150°C.
- (5) The maximum power dissipation is a function of $T_{J(MAX)}$, θ_{JA} , and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} T_A)/\theta_{JA}$. All numbers apply for packages soldered directly into a PC board.

Operating Ratings(1)

- 1				
Supply Voltage		1.8V ≤ V ⁺ ≤ 24V		
Temperature Range LM6142, LM6144	mperature Range LM6142, LM6144			
Thermal Resistance (θ_{JA})	P Package, 8-Pin PDIP	115°C/W		
	D Package, 8-Pin SOIC	193°C/W		
	NFF Package, 14-Pin PDIP	81°C/W		
	D Package, 14-Pin SOIC	126°C/W		

⁽¹⁾ Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is intended to be functional, but specific performance is not guaranteed. For guaranteed specifications and the test conditions, see the Electrical Characteristics.

5.0V DC Electrical Characteristics⁽¹⁾

Unless otherwise specified, all limits guaranteed for $T_A = 25^{\circ}C$, $V^+ = 5.0V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface limits** apply at the temperature extremes.

Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units
Vos	Input Offset Voltage		0.3	1.0	2.5	mV
				2.2	3.3	max
TCV _{OS}	Input Offset Voltage Average Drift		3			μV/°C
I _B	Input Bias Current		170	250	300	nA
		$0V \le V_{CM} \le 5V$	180	280		max
				526	526	

- (1) Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T_J = T_A. No guarantee of parametric performance is indicated in the electrical tables under conditions of the internal self heating where T_J > T_A.
- (2) Typical values represent the most likely parametric norm.
- (3) All limits are guaranteed by testing or statistical analysis.

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5.0V DC Electrical Characteristics⁽¹⁾ (continued)

Unless otherwise specified, all limits guaranteed for $T_A = 25^{\circ}C$, $V^+ = 5.0V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface limits** apply at the temperature extremes.

Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units
I _{OS}	Input Offset Current		3	30	30	nA
	·			80	80	max
R _{IN}	Input Resistance, C _M		126			ΜΩ
CMRR	Common Mode	$0V \le V_{CM} \le 4V$	107	84	84	
	Rejection Ratio	S		78	78	
		0V ≤ V _{CM} ≤ 5V	82	66	66	dB
			79	64	64	min
PSRR	Power Supply	5V ≤ V ⁺ ≤ 24V	87	80	80	
	Rejection Ratio			78	78	
V _{CM}	Input Common-Mode		-0.25	0	0	V
	Voltage Range		5.25	5.0	5.0	
A _V	Large Signal	R _L = 10k	270	100	80	V/mV
Voltage Gain			70	33	25	min
Vo	Output Swing	R _L = 100k	0.005	0.01	0.01	V
				0.013	0.013	max
			4.995	4.98	4.98	V
				4.93	4.93	min
		R _L = 10k	0.02			V max
			4.97			V min
		$R_L = 2k$	0.06	0.1	0.1	V
				0.133	0.133	max
			4.90	4.86	4.86	V
				4.80	4.80	min
I _{SC}	Output Short	Sourcing	13	10	8	mA
	Circuit Current LM6142			4.9	4	min
	LINIO142			35	35	mA
						max
		Sinking	24	10	10	mA
				5.3	5.3	min
				35	35	mA
						max
I _{SC}	Output Short	Sourcing	8	6	6	mA
	Circuit Current LM6144			3	3	min
				35	35	mA
						max
		Sinking	22	8	8	mA
				4	4	min
				35	35	mA
						max
I _S	Supply Current	Per Amplifier	650	800	800	μΑ
				880	880	max



5.0V AC Electrical Characteristics (1)

Unless Otherwise Specified, All Limits Guaranteed for $T_A = 25$ °C, $V^+ = 5.0V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface limits** apply at the temperature extremes.

Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units
SR	Slew Rate	8 V _{PP} @ V ⁺ 12V	25	15	13	V/µs
		$R_S > 1 k\Omega$		13	11	min
GBW	Gain-Bandwidth Product	f = 50 kHz	17	10	10	MHz
				6	6	min
ϕ_{m}	Phase Margin		38			Deg
	Amp-to-Amp Isolation		130			dB
e _n	Input-Referred Voltage Noise	f = 1 kHz	16			nV √Hz
i _n	Input-Referred Current Noise	f = 1 kHz	0.22			pA √Hz
T.H.D.	Total Harmonic Distortion	$f = 10 \text{ kHz}, R_L = 10 \text{ k}Ω,$	0.003			%

⁽¹⁾ Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T_J = T_A. No guarantee of parametric performance is indicated in the electrical tables under conditions of the internal self heating where T_J > T_A.

2.7V DC Electrical Characteristics(1)

Unless Otherwise Specified, All Limits Guaranteed for $T_A = 25^{\circ}C$, $V^+ = 2.7V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extreme

Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units	
V_{OS}	Input Offset Voltage		0.4	1.8	2.5	mV	
				4.3	5	max	
I _B	Input Bias Current		150	250	300	nA	
				526	526	max	
Ios	Input Offset Current		4	30	30	nA	
				80	80	max	
R _{IN}	Input Resistance		128			ΜΩ	
CMRR	Common Mode	$0V \le V_{CM} \le 1.8V$	90			dB	
	Rejection Ratio	$0V \le V_{CM} \le 2.7V$	76			min	
PSRR	Power Supply Rejection Ratio	3V ≤ V+ ≤ 5V	79				
V _{CM}	Input Common-Mode		-0.25	0	0	V min	
	Voltage Range		2.95	2.7	2.7	V max	
A _V	Large Signal	R _L = 10k	55			V/mV	
	Voltage Gain					min	
Vo	Output Swing	$R_L = 100k\Omega$	0.019	0.08	0.08	V	
				0.112	0.112	max	
			2.67	2.66	2.66	V	
				2.25	2.25	min	

⁽¹⁾ Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T_J = T_A. No guarantee of parametric performance is indicated in the electrical tables under conditions of the internal self heating where T_J > T_A.

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⁽²⁾ Typical values represent the most likely parametric norm.

⁽³⁾ All limits are guaranteed by testing or statistical analysis.

⁽²⁾ Typical values represent the most likely parametric norm.

⁽³⁾ All limits are guaranteed by testing or statistical analysis.



2.7V DC Electrical Characteristics⁽¹⁾ (continued)

Unless Otherwise Specified, All Limits Guaranteed for $T_A = 25$ °C, $V^+ = 2.7V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extreme

Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units
Is	Supply Current	Per Amplifier	510	800	800	μA
				880	880	max

2.7V AC Electrical Characteristics(1)

Unless Otherwise Specified, All Limits Guaranteed for $T_A = 25^{\circ}C$, $V^+ = 2.7V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extreme

Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units
GBW	Gain-Bandwidth Product	f = 50 kHz	9			MHz
φ _m	Phase Margin		36			Deg
G _m	Gain Margin		6			dB

⁽¹⁾ Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T_J = T_A. No guarantee of parametric performance is indicated in the electrical tables under conditions of the internal self heating where T_J > T_A.

24V Electrical Characteristics(1)

Unless Otherwise Specified, All Limits Guaranteed for $T_A = 25$ °C, $V^+ = 24V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extreme

Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units	
Vos	Input Offset Voltage		1.3	2	3.8	mV	
				4.8	4.8	max	
I _B	Input Bias Current		174			nA max	
I _{OS}	Input Offset Current		5			nA max	
R _{IN}	Input Resistance		288			ΜΩ	
CMRR	Common Mode	0V ≤ V _{CM} ≤ 23V	114			dB	
	Rejection Ratio	$0V \le V_{CM} \le 24V$	100			min	
PSRR	Power Supply Rejection Ratio	$0V \le V_{CM} \le 24V$	87				
V _{CM}	Input Common-Mode		-0.25	0	0	V min	
	Voltage Range		24.25	24	24	V max	
A _V	Large Signal Voltage Gain	R _L = 10k	500			V/mV min	
Vo	Output Swing	R _L = 10 kΩ	0.07	0.15	0.15	V	
				0.185	0.185	max	
			23.85	23.81	23.81	V	
				23.62	23.62	min	

⁽¹⁾ Electrical Table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device such that T_J = T_A. No guarantee of parametric performance is indicated in the electrical tables under conditions of the internal self heating where T_J > T_A.

⁽²⁾ Typical values represent the most likely parametric norm.

⁽³⁾ All limits are guaranteed by testing or statistical analysis.

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⁽³⁾ All limits are guaranteed by testing or statistical analysis.



24V Electrical Characteristics⁽¹⁾ (continued)

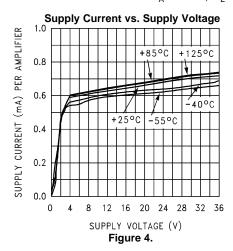
Unless Otherwise Specified, All Limits Guaranteed for $T_A = 25^{\circ}C$, $V^+ = 24V$, $V^- = 0V$, $V_{CM} = V_O = V^+/2$ and $R_L > 1$ M Ω to $V^+/2$. **Boldface** limits apply at the temperature extreme

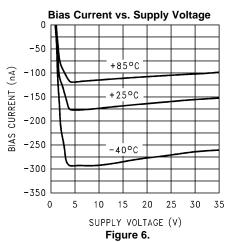
Symbol	Parameter	Conditions	Typ ⁽²⁾	LM6144AI LM6142AI Limit ⁽³⁾	LM6144BI LM6142BI Limit ⁽³⁾	Units
Is	Supply Current	Per Amplifier	750	1100	1100	μΑ
				1150	1150	max
GBW	Gain-Bandwidth Product	f = 50 kHz	18			MHz

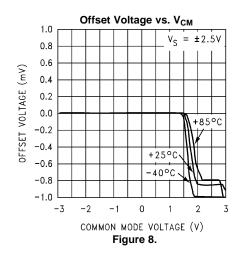


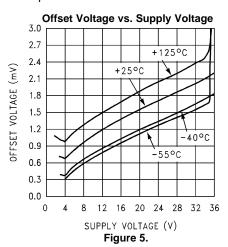
Typical Performance Characteristics

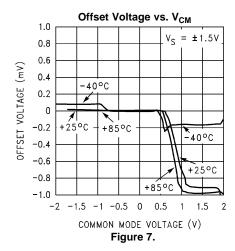
 $T_A = 25$ °C, $R_L = 10 \text{ k}\Omega$ Unless Otherwise Specified

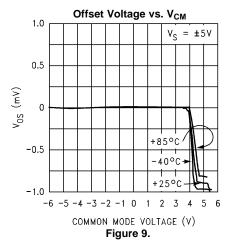






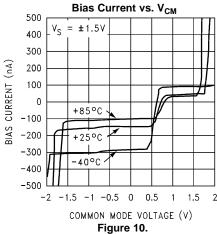












Bias Current vs. V_{CM} 500 400 $= \pm 5 V$ 300 BIAS CURRENT (nA) 200 100 0 +85°C -100 -200 -300 -40°C -400 -500

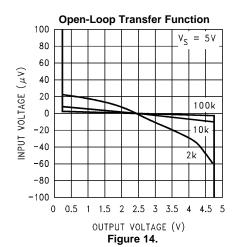
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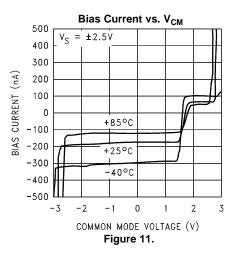
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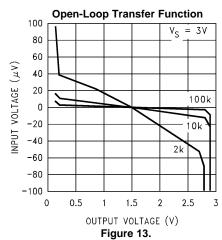
COMMON MODE VOLTAGE (V)

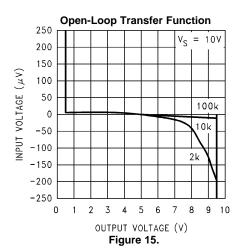
Figure 12.

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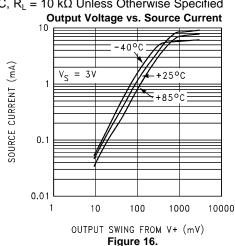


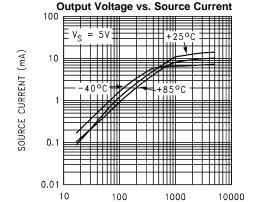






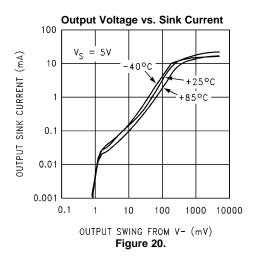


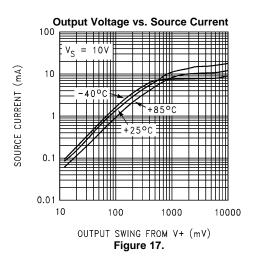


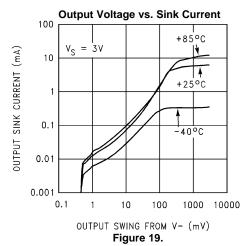


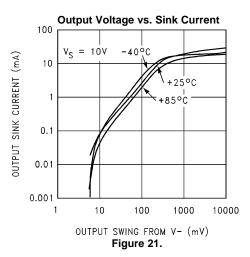
OUTPUT SWING FROM V+ (mV)

Figure 18.



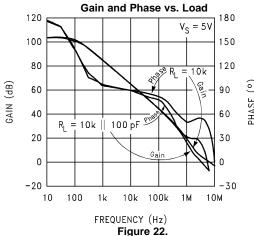


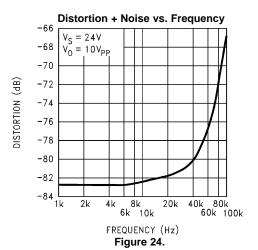


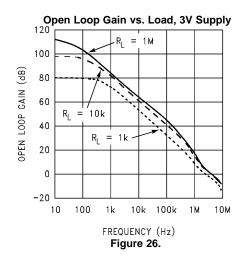


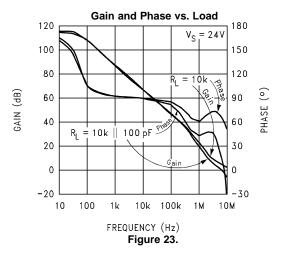


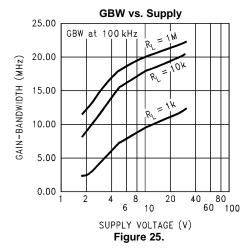


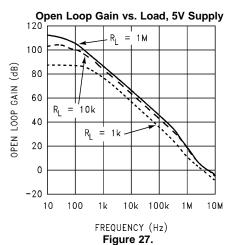








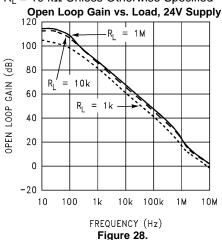




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 $T_A = 25$ °C, $R_L = 10 \text{ k}\Omega$ Unless Otherwise Specified



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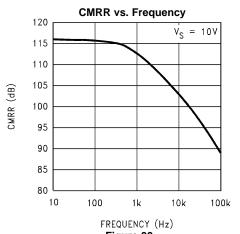
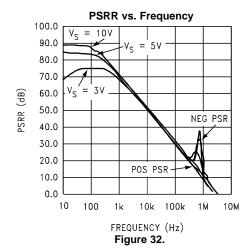
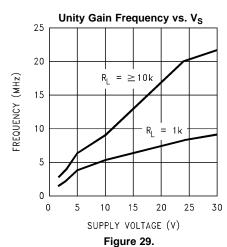


Figure 30.





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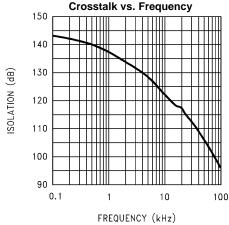


Figure 31.

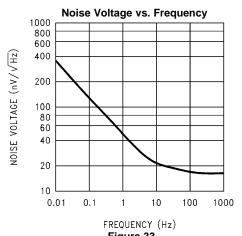
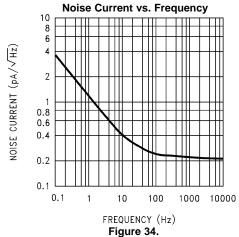
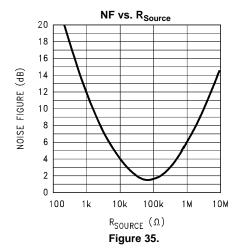


Figure 33.



 $T_A = 25$ °C, $R_L = 10 \text{ k}\Omega$ Unless Otherwise Specified







LM6142/LM6144 APPLICATION IDEAS

The LM6142 brings a new level of ease of use to op amp system design.

With greater than rail-to-rail input voltage range concern over exceeding the common-mode voltage range is eliminated.

Rail-to-rail output swing provides the maximum possible dynamic range at the output. This is particularly important when operating on low supply voltages.

The high gain-bandwidth with low supply current opens new battery powered applications, where high power consumption, previously reduced battery life to unacceptable levels.

To take advantage of these features, some ideas should be kept in mind.

ENHANCED SLEW RATE

Unlike most bipolar op amps, the unique phase reversal prevention/speed-up circuit in the input stage causes the slew rate to be very much a function of the input signal amplitude.

Figure 36 shows how excess input signal, is routed around the input collector-base junctions, directly to the current mirrors.

The LM6142/LM6144 input stage converts the input voltage change to a current change. This current change drives the current mirrors through the collectors of Q1–Q2, Q3–Q4 when the input levels are normal.

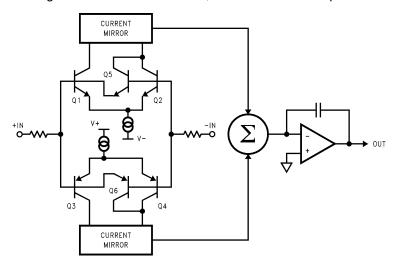


Figure 36.

If the input signal exceeds the slew rate of the input stage, the differential input voltage rises above two diode drops. This excess signal bypasses the normal input transistors, (Q1–Q4), and is routed in correct phase through the two additional transistors, (Q5, Q6), directly into the current mirrors.

This rerouting of excess signal allows the slew-rate to increase by a factor of 10 to 1 or more. (See Figure 37.)

As the overdrive increases, the op amp reacts better than a conventional op amp. Large fast pulses will raise the slew- rate to around 30V to 60V/µs.

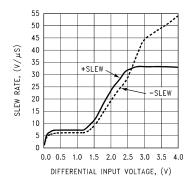


Figure 37. Slew Rate vs. ΔV_{IN} $V_S = \pm 5V$

This effect is most noticeable at higher supply voltages and lower gains where incoming signals are likely to be large.

This new input circuit also eliminates the phase reversal seen in many op amps when they are overdriven.

This speed-up action adds stability to the system when driving large capacitive loads.

DRIVING CAPACITIVE LOADS

Capacitive loads decrease the phase margin of all op amps. This is caused by the output resistance of the amplifier and the load capacitance forming an R-C phase lag network. This can lead to overshoot, ringing and oscillation. Slew rate limiting can also cause additional lag. Most op amps with a fixed maximum slew-rate will lag further and further behind when driving capacitive loads even though the differential input voltage raises. With the LM6142, the lag causes the slew rate to raise. The increased slew-rate keeps the output following the input much better. This effectively reduces phase lag. After the output has caught up with the input, the differential input voltage drops down and the amplifier settles rapidly.

These features allow the LM6142 to drive capacitive loads as large as 1000pF at unity gain and not oscillate. The scope photos (Figure 38 and Figure 39) above show the LM6142 driving a l000pF load. In Figure 38, the upper trace is with no capacitive load and the lower trace is with a 1000pF load. Here we are operating on ± 12 V supplies with a 20 V_{PP} pulse. Excellent response is obtained with a C_f of l0pF. In Figure 39, the supplies have been reduced to ± 2.5 V, the pulse is 4 V_{PP} and C_f is 39pF. The best value for the compensation capacitor is best established after the board layout is finished because the value is dependent on board stray capacity, the value of the feedback resistor, the closed loop gain and, to some extent, the supply voltage.

Another effect that is common to all op amps is the phase shift caused by the feedback resistor and the input capacitance. This phase shift also reduces phase margin. This effect is taken care of at the same time as the effect of the capacitive load when the capacitor is placed across the feedback resistor.

The circuit shown in Figure 40 was used for these scope photos.

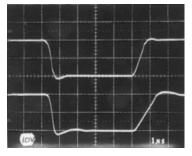


Figure 38.



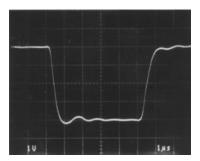


Figure 39.

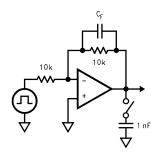


Figure 40.

Typical Applications

FISH FINDER/ DEPTH SOUNDER.

The LM6142/LM6144 is an excellent choice for battery operated fish finders. The low supply current, high gain-bandwidth and full rail to rail output swing of the LM6142 provides an ideal combination for use in this and similar applications.

ANALOG TO DIGITAL CONVERTER BUFFER

The high capacitive load driving ability, rail-to-rail input and output range with the excellent CMR of 82 dB, make the LM6142/LM6144 a good choice for buffering the inputs of A to D converters.

3 OP AMP INSTRUMENTATION AMP WITH RAIL-TO-RAIL INPUT AND OUTPUT

Using the LM6144, a 3 op amp instrumentation amplifier with rail-to-rail inputs and rail to rail output can be made. These features make these instrumentation amplifiers ideal for single supply systems.

Some manufacturers use a precision voltage divider array of 5 resistors to divide the common-mode voltage to get an input range of rail-to-rail or greater. The problem with this method is that it also divides the signal, so to even get unity gain, the amplifier must be run at high closed loop gains. This raises the noise and drift by the internal gain factor and lowers the input impedance. Any mismatch in these precision resistors reduces the CMR as well. Using the LM6144, all of these problems are eliminated.

In this example, amplifiers A and B act as buffers to the differential stage (Figure 41). These buffers assure that the input impedance is over $100M\Omega$ and they eliminate the requirement for precision matched resistors in the input stage. They also assure that the difference amp is driven from a voltage source. This is necessary to maintain the CMR set by the matching of R1–R2 with R3–R4.



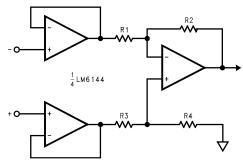


Figure 41.

The gain is set by the ratio of R2/R1 and R3 should equal R1 and R4 equal R2. Making R4 slightly smaller than R2 and adding a trim pot equal to twice the difference between R2 and R4 will allow the CMR to be adjusted for optimum.

With both rail to rail input and output ranges, the inputs and outputs are only limited by the supply voltages. Remember that even with rail-to-rail output, the output can not swing past the supplies so the combined common mode voltage plus the signal should not be greater than the supplies or limiting will occur.

SPICE MACROMODEL

A SPICE macromodel of this and many other Texas Instruments op amps is available http://www.ti.com/ww/en/analog/webench/index.shtml?DCMP=hpa_sva_webench&HQS=webench-bb.





REVISION HISTORY

Cł	hanges from Revision C (March 2013) to Revision D	Pag	ge
•	Changed layout of National Data Sheet to TI format		16





1-Nov-2013

PACKAGING INFORMATION

Orderable Device	Status	Package Type	Package Drawing	Pins	Package Qty	Eco Plan	Lead/Ball Finish (6)	MSL Peak Temp	Op Temp (°C)	Device Marking (4/5)	Samples
LM6142AIM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 85	LM614 2AIM	
LM6142AIM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM614 2AIM	Samples
LM6142AIMX	NRND	SOIC	D	8	2500	TBD	Call TI	Call TI	-40 to 85	LM614 2AIM	
LM6142AIMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM614 2AIM	Samples
LM6142BIM	NRND	SOIC	D	8	95	TBD	Call TI	Call TI	-40 to 85	LM614 2BIM	
LM6142BIM/NOPB	ACTIVE	SOIC	D	8	95	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM614 2BIM	Samples
LM6142BIMX	NRND	SOIC	D	8	2500	TBD	Call TI	Call TI	-40 to 85	LM614 2BIM	
LM6142BIMX/NOPB	ACTIVE	SOIC	D	8	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM614 2BIM	Samples
LM6142BIN/NOPB	ACTIVE	PDIP	Р	8	40	Green (RoHS & no Sb/Br)	CU SN	Level-1-NA-UNLIM	-40 to 85	LM6142 BIN	Samples
LM6144AIM	NRND	SOIC	D	14	55	TBD	Call TI	Call TI	-40 to 85	LM6144 AIM	
LM6144AIM/NOPB	ACTIVE	SOIC	D	14	55	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM6144 AIM	Samples
LM6144AIMX	NRND	SOIC	D	14	2500	TBD	Call TI	Call TI	-40 to 85	LM6144 AIM	
LM6144AIMX/NOPB	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM6144 AIM	Samples
LM6144BIM	NRND	SOIC	D	14	55	TBD	Call TI	Call TI	-40 to 85	LM6144 BIM	
LM6144BIM/NOPB	ACTIVE	SOIC	D	14	55	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM6144 BIM	Samples
LM6144BIMX	NRND	SOIC	D	14	2500	TBD	Call TI	Call TI	-40 to 85	LM6144 BIM	
LM6144BIMX/NOPB	ACTIVE	SOIC	D	14	2500	Green (RoHS & no Sb/Br)	CU SN	Level-1-260C-UNLIM	-40 to 85	LM6144 BIM	Samples



PACKAGE OPTION ADDENDUM

1-Nov-2013

Orderable Device	Status	Package Type	•	Pins	_	Eco Plan	Lead/Ball Finish	MSL Peak Temp	Op Temp (°C)	Device Marking	Samples
	(1)		Drawing		Qty	(2)	(6)	(3)		(4/5)	
LM6144BIN/NOPB	ACTIVE	PDIP	NFF	14	25	Green (RoHS & no Sb/Br)	SN	Level-1-NA-UNLIM	-40 to 85	LM6144BIN	Samples

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

- (3) MSL, Peak Temp. The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.
- (4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.
- (5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.
- (6) Lead/Ball Finish Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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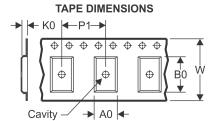
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PACKAGE MATERIALS INFORMATION

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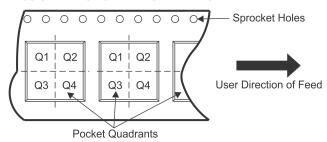
TAPE AND REEL INFORMATION





	Dimension designed to accommodate the component width
	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

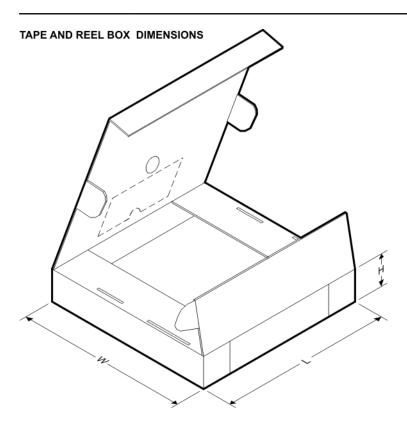
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing		SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
LM6142AIMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM6142AIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM6142BIMX	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM6142BIMX/NOPB	SOIC	D	8	2500	330.0	12.4	6.5	5.4	2.0	8.0	12.0	Q1
LM6144AIMX	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1
LM6144AIMX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1
LM6144BIMX	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1
LM6144BIMX/NOPB	SOIC	D	14	2500	330.0	16.4	6.5	9.35	2.3	8.0	16.0	Q1

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*All dimensions are nominal

Device	Device Package Type		Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
LM6142AIMX	SOIC	D	8	2500	367.0	367.0	35.0
LM6142AIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM6142BIMX	SOIC	D	8	2500	367.0	367.0	35.0
LM6142BIMX/NOPB	SOIC	D	8	2500	367.0	367.0	35.0
LM6144AIMX	SOIC	D	14	2500	367.0	367.0	35.0
LM6144AIMX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0
LM6144BIMX	SOIC	D	14	2500	367.0	367.0	35.0
LM6144BIMX/NOPB	SOIC	D	14	2500	367.0	367.0	35.0

P (R-PDIP-T8)

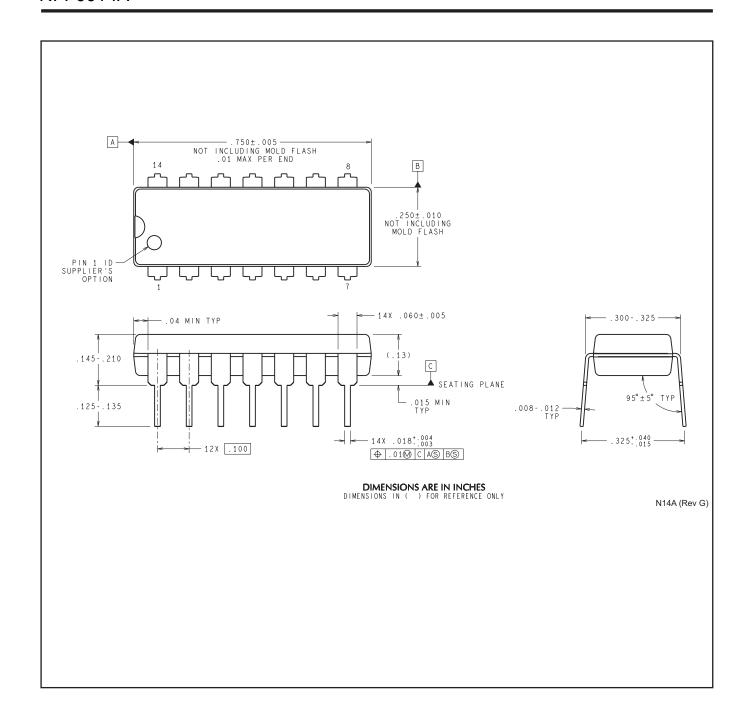
PLASTIC DUAL-IN-LINE PACKAGE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- C. Falls within JEDEC MS-001 variation BA.

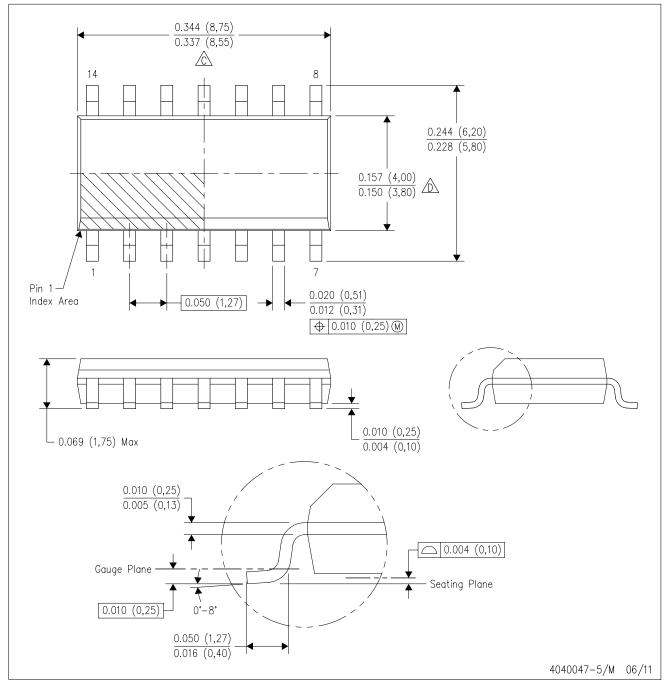






D (R-PDSO-G14)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AB.



D (R-PDSO-G8)

PLASTIC SMALL OUTLINE



NOTES:

- A. All linear dimensions are in inches (millimeters).
- B. This drawing is subject to change without notice.
- Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
- Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
- E. Reference JEDEC MS-012 variation AA.



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